



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-01
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SPC560B60L7CE0X	B91T*FB64BDQ	A	MA1A	2016-06-01
Amount	UoM	Unit type	ST ECOPACK Grade	
1650.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	24x24x1.4	176	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th Dec 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	B91T*FB64BDQ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	27.028	mg	supplier	die	Silicon (Si)	7440-21-3		23.092	mg	854373	13995
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.043	mg	1591	26
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.379	mg	14022	230
Die				supplier	metallization	Tantalum (Ta)	7440-25-7		3.165	mg	117101	1918
Die				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	37	1
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	148	2
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	111	2
Die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.096	mg	3552	58
Die				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0.245	mg	9065	148
Leadframe	Copper & its alloys	432.443	mg	supplier	alloy	Copper (Cu)	7440-50-8		403.257	mg	932509	244398
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		12.576	mg	29081	7622
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.629	mg	1455	381
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		2.725	mg	6301	1652
Leadframe				supplier	tape	bismaleimide	35325-39-4		0.095	mg	220	58
Leadframe				supplier	tape	poly(4,4'-oxydiphenylene-pyromellitimide)	25036-53-7		9.338	mg	21594	5659
Leadframe				supplier	tape	Zn(OH)2	20427-58-1		0.095	mg	220	58
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		3.728	mg	8621	2259
Die attach		4.847	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		3.818	mg	787704	2314
Die attach				supplier	glue or tape	Urethane acrylate oligomer	na		0.339	mg	69940	205
Die attach				supplier	glue or tape	Methacrylate	na		0.339	mg	69940	205
Die attach				supplier	glue or tape	Acrylate	na		0.339	mg	69940	205
Die attach				SVHC	glue or tape	NMP	872-50-4		0.012	mg	2476	7
Bonding wire				supplier	wire	Copper (Cu)	7440-50-8		1.332	mg	980854	807
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.024	mg	17673	15
Bonding wire				supplier	wire	Silver (Ag)	7440-22-4		0.002	mg	1473	1
encapsulation		1173.674	mg	supplier	mold compound	Epoxy Resin	Proprietary		85.878	mg	73170	52047
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		85.878	mg	73170	52047
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		989.323	mg	842928	599590
encapsulation				supplier	mold compound	Quartz	14808-60-7		3.435	mg	2927	2082
encapsulation				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		5.725	mg	4878	3470
encapsulation				supplier	mold compound	Carbon black	1333-86-4		3.435	mg	2927	2082
connections coating	Solder	10.116	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		10.116	mg	1000000	6131